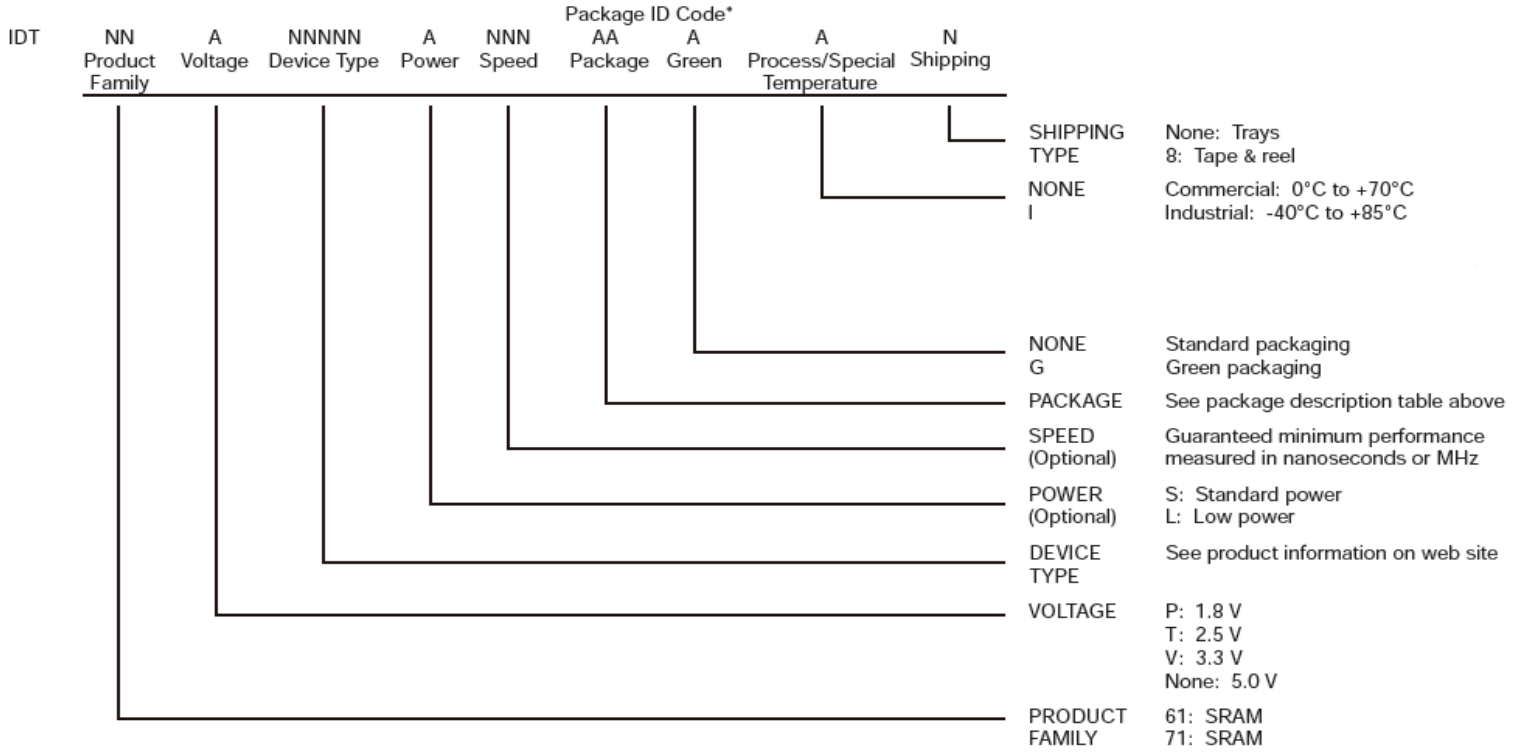
# SRAM Products
# Ordering Information

## Package Description Table

| IDT ID | Abbr. | Description | IDT ID | Abbr. | Description |
|---|---|---|---|---|---|
| BE | CABGA | Chip Array Ball Grid Array | SO | SOIC | Small Outline Integrated Circuit |
| BF | CABGA | Chip Array Ball Grid Array | TY | SOJ | Small Outline J Form |
| BQ | CABGA | Chip Array Ball Grid Array | Y | SOJ | Small Outline J Form |
| D | CDIP | Ceramic Dual In-line Package | Y | SOJ | Small Outline J Form (300 mil) |
| TD | CDIP | Ceramic Dual In-line Package | Y | SOJ | Small Outline J Form (400 mil) |
| L | LCC | Leadless Chip Carrier | PF | TQFP | Thin Quad Flat Package |
| BG | PBGA | Plastic Ball Grid Array | PH | TSOP | Thin Small Outline Package (Type II) |
| TP | PDIP | Plastic Dual In-line Package | PZ | TSOP | Thin Small Outline Package |

## Part Number Description

A = Alpha Character  N = Numeric Character




* Please see "Packaging Overview" section for IDT package ID codes.